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PMP11414 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1	1	1uF	C0603C105K3RACTU	Kemet	CAP, CERM, 1 µF, 25 V, +/- 10%, X7R, 0603_950	0603_950
C2, C3, C9, C60	4	4.7uF	C0603C475K8PACTU	Kemet	CAP, CERM, 4.7 µF, 10 V, +/- 10%, X5R, 0603	0603
C4	1	4.7pF	GRM1555C1H4R7CA01D	MuRata	CAP, CERM, 4.7 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
C5, C6, C7, C8	4	0.047uF	C1005X7R1C473K	TDK	CAP, CERM, 0.047 µF, 16 V, +/- 10%, X7R, 0402	0402
C10, C12, C16, C17, C18, C19, C20, C28, C55, C56, C57, C58	12	0.1uF	C1005X7R1H104K	TDK	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0402	0402
C11, C13, C14, C15	4	22pF	C1005C0G1H220J050BA	TDK	CAP, CERM, 22 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
C21, C23, C24	3	1000pF	C1005X7R1H102K	TDK	CAP, CERM, 1000 pF, 50 V, +/- 10%, X7R, 0402	0402
C22	1	100pF	C0402C101J3GACTU	Kemet	CAP, CERM, 100 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
C25, C26, C27, C29	4	680pF	C1005C0G1E681J	TDK	CAP, CERM, 680 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
C30, C31, C32, C33	4	22uF	C3216X5R1E226M160AB	TDK	CAP, CERM, 22 µF, 25 V, +/- 20%, X5R, 1206_190	1206_190
C34, C35, C36, C37	4	0.1uF	C1005X5R1A104K	TDK	CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	0402
C38, C39, C40, C41, C42, C43, C44, C45	8	22uF	C1608X5R0J226M080AC	TDK	CAP, CERM, 22 µF, 6.3 V, +/- 20%, X5R, 0603	0603
C46, C47, C48, C49, C50, C51, C52, C53	8	100uF	GRM31CR60J107ME39L	MuRata	CAP, CERM, 100 µF, 6.3 V, +/- 20%, X5R, 1206	1206
C54	1	220uF	EEE-FC1C221P	Panasonic	CAP, AL, 220 µF, 16 V, +/- 20%, 0.15 ohm, SMD	SMT Radial G
C61	1	470uF	4TPF470M5EL	Panasonic	CAP, Tantalum Polymer, 470 µF, 4 V, +/- 20%, 0.005 ohm, 7.3x2.8x4.3mm SMD	7.3x2.8x4.3mm
J1, J2, J3, J4	4		U.FL-R-SMT-1	Hirose Electric Co. Ltd.	Connector, Ultra-Mini Coaxial, SMD	Ultra small CO-AX SMD
J5, J6, J7, J8, J9	5		ED120/2DS	On-Shore Technology	TERMINAL BLOCK 5.08MM VERT 2POS, TH	TERM_BLK, 2pos, 5.08mm
L1, L2	2	2.2uH	XAL5030-222MEB	Coilcraft	Inductor, Shielded, Composite, 2.2 µH, 9.2 A, 0.01 ohm, SMD	5.3x31.x5.5mm
L3, L4	2	2.2uH	XAL4020-222MEB	Coilcraft	Inductor, Shielded, Composite, 2.2 µH, 5.5 A, 0.04 ohm, SMD	4x2.1x4mm
P2, P3, P4, P5	4		TSW-102-07-G-S	Samtec	Header, TH, 100mil, 2x1, Gold plated, 230 mil above insulator	TSW-102-07-G-S
P6	1		TSW-103-07-G-S	Samtec	Header, TH, 100mil, 3x1, Gold plated, 230 mil above insulator	TSW-103-07-G-S
R1, R2, R3, R4	4	4.7k	CRCW04024K70JNED	Vishay-Dale	RES, 4.7 k, 5%, 0.063 W, 0402	0402
R5	1	374k	CRCW0402374KFKED	Vishay-Dale	RES, 374 k, 1%, 0.063 W, 0402	0402
R6, R16, R20, R42	4	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
R9, R11, R13, R15	4	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
R10	1	20.0k	CRCW040220K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.063 W, 0402	0402
R12, R14	2	10.5k	CRCW040210K5FKED	Vishay-Dale	RES, 10.5 k, 1%, 0.063 W, 0402	0402
R17, R18	2	30.1k	CRCW040230K1FKED	Vishay-Dale	RES, 30.1 k, 1%, 0.063 W, 0402	0402
R19, R23	2	24.9k	CRCW040224K9FKED	Vishay-Dale	RES, 24.9 k, 1%, 0.063 W, 0402	0402
R21	1	13.0k	CRCW040213K0FKED	Vishay-Dale	RES, 13.0 k, 1%, 0.063 W, 0402	0402
R22	1	22.1k	CRCW040222K1FKED	Vishay-Dale	RES, 22.1 k, 1%, 0.063 W, 0402	0402

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R24	1	30.9k	CRCW040230K9FKED	Vishay-Dale	RES, 30.9 k, 1%, 0.063 W, 0402	0402
R25, R26, R27, R28	4	10.0	CRCW040210R0FKED	Vishay-Dale	RES, 10.0, 1%, 0.063 W, 0402	0402
R29, R30, R31, R32	4	49.9	CRCW040249R9FKED	Vishay-Dale	RES, 49.9, 1%, 0.063 W, 0402	0402
R37, R39	2	1.10Meg	CRCW04021M10FKED	Vishay-Dale	RES, 1.10 M, 1%, 0.063 W, 0402	0402
R40	1	887k	CRCW0402887KFKED	Vishay-Dale	RES, 887 k, 1%, 0.063 W, 0402	0402
U1	1		TPS65400RGZ	Texas Instruments	4.3V TO 18V INPUT FLEXIBLE POWER MANAGEMENT UNIT WITH PMBus/ I2C AND INTEGRATED SEQUENCING, RGZ0048G	RGZ0048G
C62	0	470uF	4TPF470M5EL	Panasonic	CAP, Tantalum Polymer, 470 µF, 4 V, +/- 20%, 0.005 ohm, 7.3x2.8x4.3mm SMD	7.3x2.8x4.3mm
R7, R8	0	1.0k	CRCW04021K00JNED	Vishay-Dale	RES, 1.0 k, 5%, 0.063 W, 0402	0402
R38	0	100k	CRCW0402100KFKED	Vishay-Dale	RES, 100 k, 1%, 0.063 W, 0402	0402

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